

CHIP COMMON MODE CHOKES FASCCM2012,2012HS SERIES



FEATURES :

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission

APPLICATIONS:

MIPI, MHL serial interface in mobile device

GENERAL SPECIFICATIONS:

Rated current:0.1A to 0.5A
Parameters Test Temp:25°C
Test Frequency:100MHz
Operating temperature:-20°C to +85°C
Storage Temp:-0°C to +40°C
Resistance to Soldering Heat:260°C for 10 sec
Temperature Rise:40°C Typ. at Rated Current
All parts meet ROHS compliance

ELECTRICAL CHARACTERISTICS

Part Number	Impedance [ohm]±25%	D.C.R [ohm]Max at 25°C	Rated current [mA]Max	Rated Voltage [V]	Withstand Voltage [V]	Part Number	Impedance [ohm]±25% Common Mode	D.C.R [ohm]Max at 25°C	Rated current [mA]Max	Rated Voltage [V]	Impedance [ohm]Max Differential Mode
FASCCM2012-670	67	0.40	400	10	200	FASCCM2012HSH-670A	67	1.0	200	10	100
FASCCM2012-900	90	0.40	400	10	200	FASCCM2012HSH-900A	90	1.0	200	10	100
FASCCM2012-121	120	0.40	400	10	200	FASCCM2012HSD-500A	50	1.0	100	10	100
FASCCM2012-161	160	0.50	400	10	200	FASCCM2012HSD-900A	90	1.0	200	10	100
FASCCM2012-181	180	0.50	400	10	200	FASCCM2012HSD-121A	120	1.2	100	10	100
FASCCM2012-221	220	0.50	300	10	200	FASCCM2012HSS-500A	50	1.0	100	10	100

TECHNICAL INFORMATION AND PAD LAYOUT:

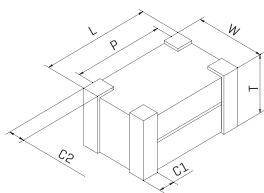


FIG1.

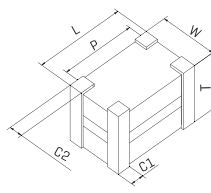
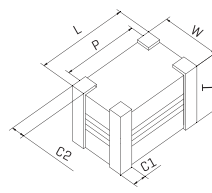
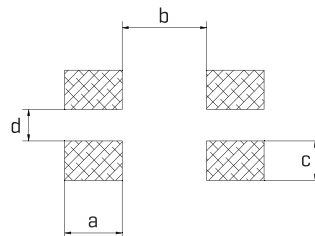
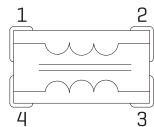


FIG2.



FASCCM2012HSS-500A FIG2.



DIMENSIONS:MM

Part number	L	W	T	P	C1	C2	a	b	c	d	FIG
FASCCM2012	2.00±0.2	1.25±0.2	1.00±0.1	1.60±0.2	0.40±0.2	0.30±0.2	0.75 REF	1.10 REF	0.50 REF	0.40 REF	1
FASCCM2012HS	2.00±0.2	1.20±0.2	1.00±0.2	1.60±0.2	0.40±0.2	0.30±0.2	0.75 REF	1.10 REF	0.50 REF	0.4 REF	2